



ZHEJIANG UNIÜ-NE Technology CO., LTD

浙江宇力微新能源科技有限公司



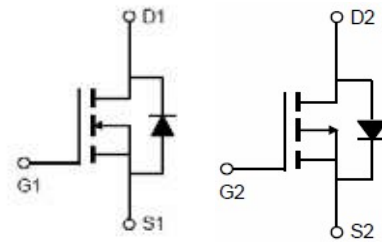
## AP3003 Data Sheet

V 1.1

版权归浙江宇力微新能源科技有限公司

**Description**

The AP3003 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge. This device is suitable for use as a Battery protection or in other Switching application.

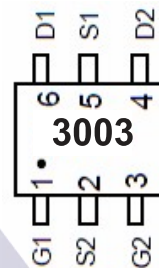


**General Features**

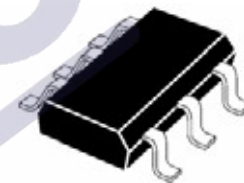
- **N-Channel**
- $V_{DS} = 30V, I_D = 4.2A$   
 $R_{DS(ON)} < 24m\Omega @ V_{GS}=10V$   
 $R_{DS(ON)} < 28m\Omega @ V_{GS}=4.5V$
- **P-Channel**
- $V_{DS} = -30V, I_D = -3.7A$   
 $R_{DS(ON)} < 65 m\Omega @ V_{GS}=-10V$   
 $R_{DS(ON)} < 85 m\Omega @ V_{GS}=-4.5V$

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Halogen-free

N-channel P-channel  
Schematic diagram



Marking and pin Assignment



TSOT23-6L top view

**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3003	AP3003S6	TSOT23-6L	Ø180mm	8mm	3000units

**Absolute Maximum Ratings ( $T_A=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage	$V_{DS}$	30	-30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 12$	$\pm 12$	V	
Continuous Drain Current	$I_D$	$T_A=25^\circ C$	4.2	-3.7	A
		$T_A=70^\circ C$	3	-2.1	
Pulsed Drain Current (Note 1)	$I_{DM}$	20	-15	A	
Maximum Power Dissipation	$P_D$	1.2		W	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	-55 To 150	$^\circ C$	

**Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	104	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	P-Ch	104	$^\circ C/W$

**N-CH Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.7	-	1.3	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4.2A	-	19	24	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A	-	24	28	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =3.1A	-	4	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1.0MHz	-	210	-	PF
Output Capacitance	C <sub>oss</sub>		-	35	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	23	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, R <sub>L</sub> =3Ω V <sub>GS</sub> =10V, R <sub>GEN</sub> =6Ω	-	4.5	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	1.5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	18.5	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	15.5	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =3.5A, V <sub>GS</sub> =10V	-	5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	0.55	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	1	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =3.5A	-	0.8	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	3.5	A

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

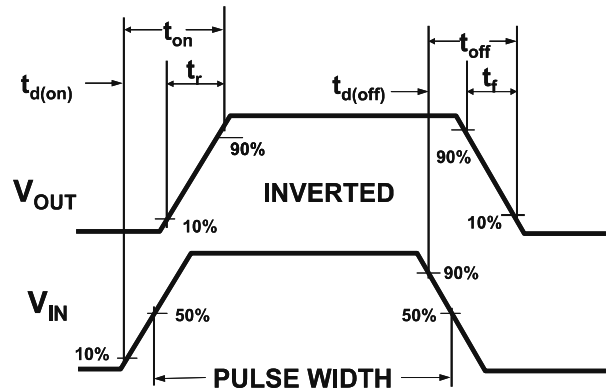
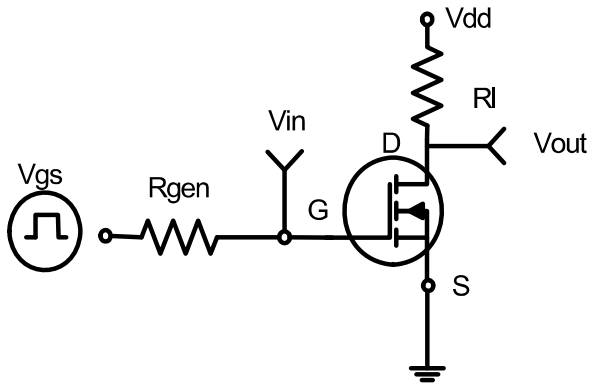
**P-CH Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-30	-33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.7	-	-1.3	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-3.7A	-	50	65	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A		60	85	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-2.7A		2	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1.0MHz	-	199	-	PF
Output Capacitance	C <sub>OSS</sub>		-	47	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	28	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V, R <sub>L</sub> =15Ω V <sub>GS</sub> =-10V, R <sub>GEN</sub> =6Ω	-	8	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	12	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	4	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V, I <sub>D</sub> =-2.7A, V <sub>GS</sub> =-10V	-	5	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	0.7	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	1.1	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-2.7A	-	-	-1.2	V

**Notes:**

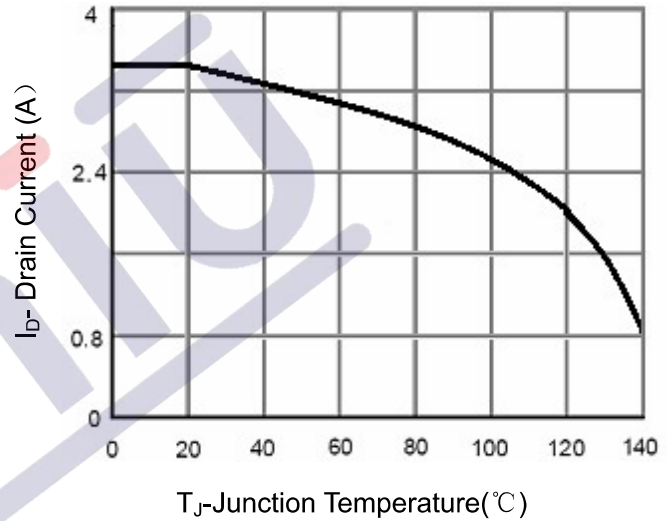
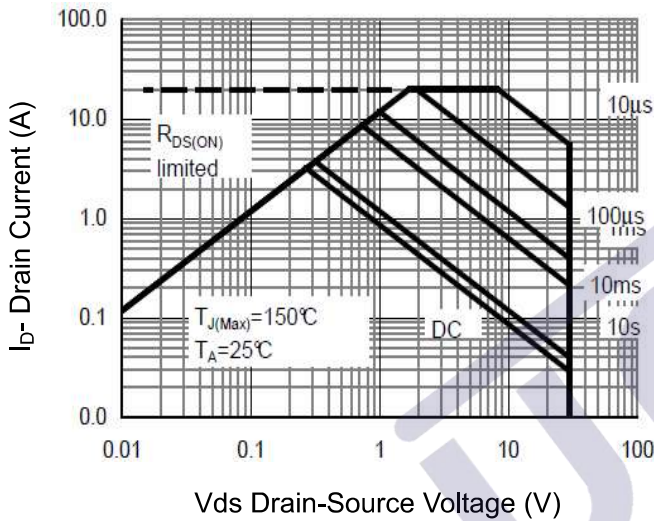
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

**N- Channel Typical Electrical and Thermal Characteristics**



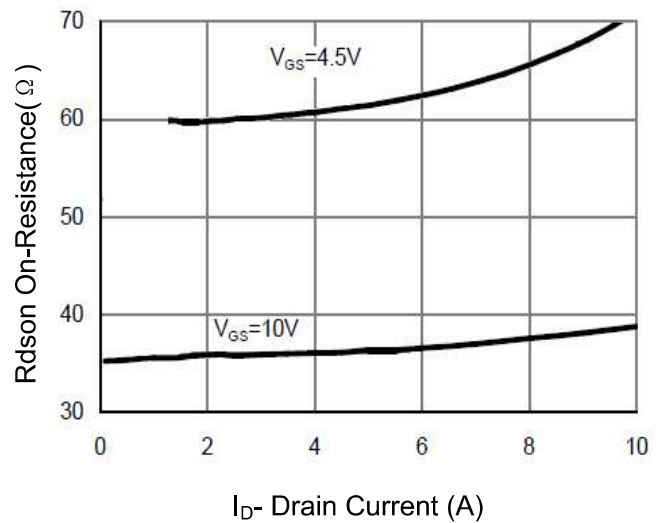
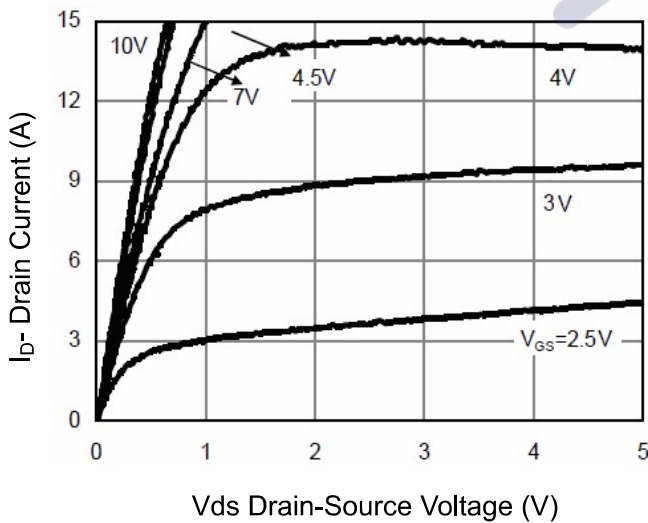
**Figure 1: Switching Test Circuit**

**Figure 2: Switching Waveforms**



**Figure 3 Safe Operation Area**

**Figure 4 Drain Current**



**Figure 5 Output Characteristics**

**Figure 6 Drain-Source On-Resistance**

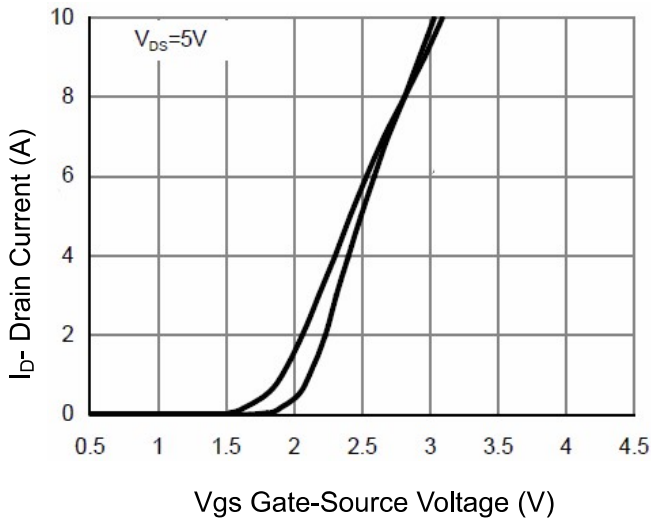


Figure 7 Transfer Characteristics

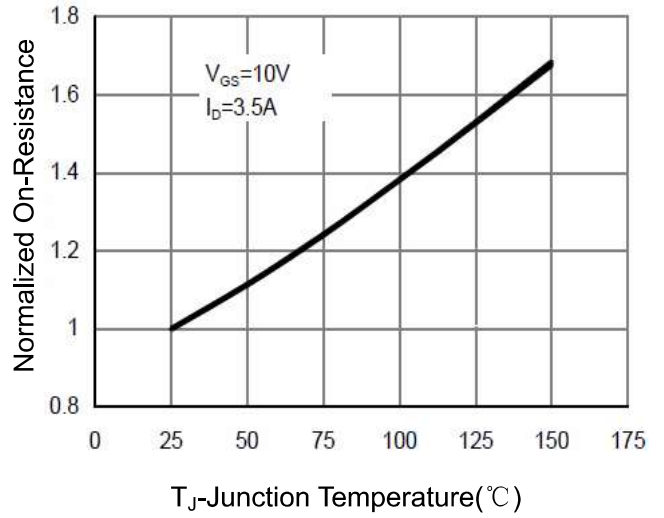


Figure 8 Drain-Source On-Resistance

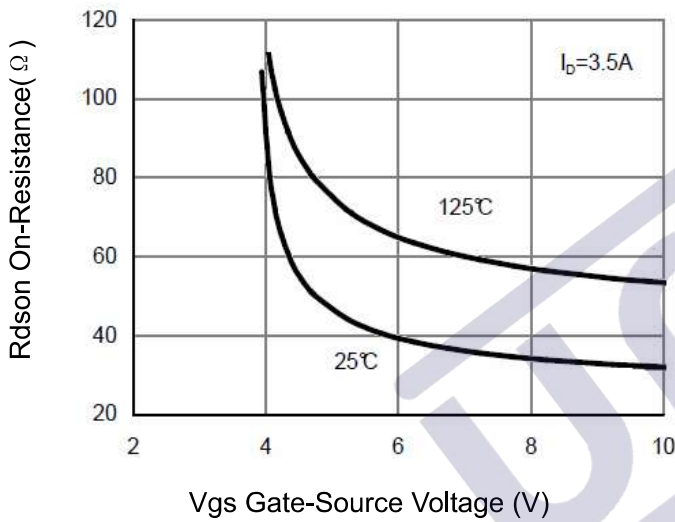


Figure 9 Rdson vs Vgs

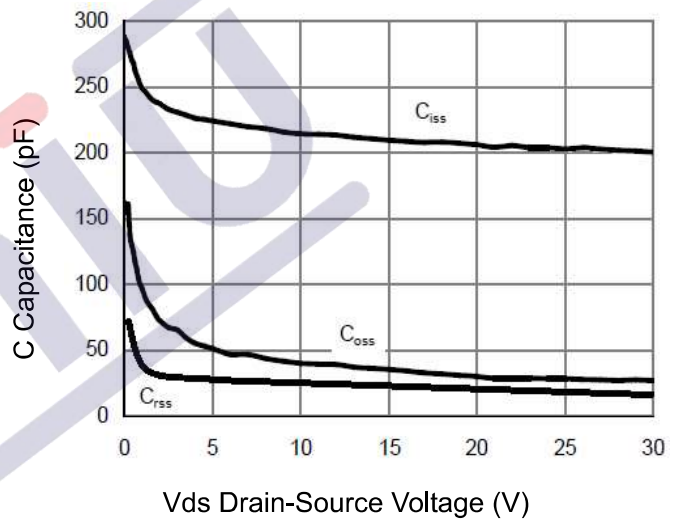


Figure 10 Capacitance vs Vds

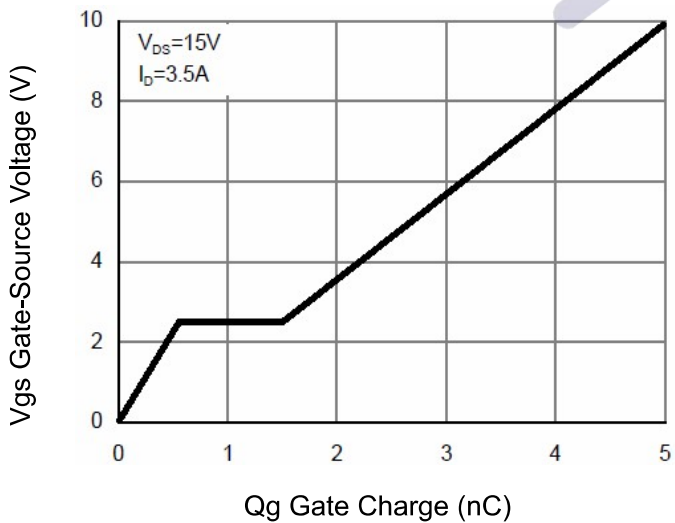


Figure 11 Gate Charge

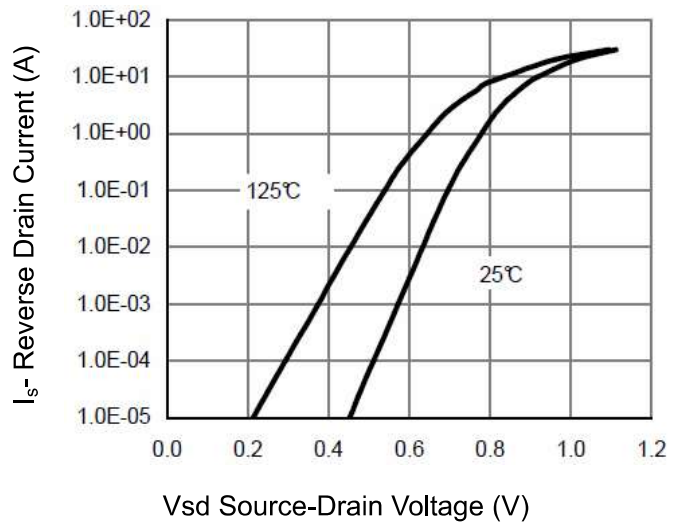


Figure 12 Source- Drain Diode Forward

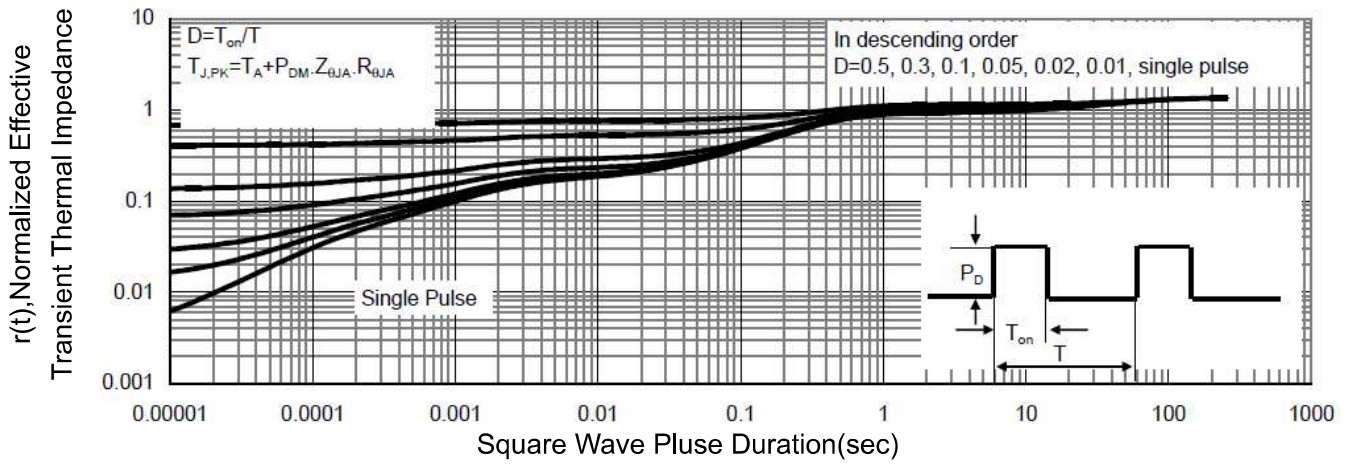
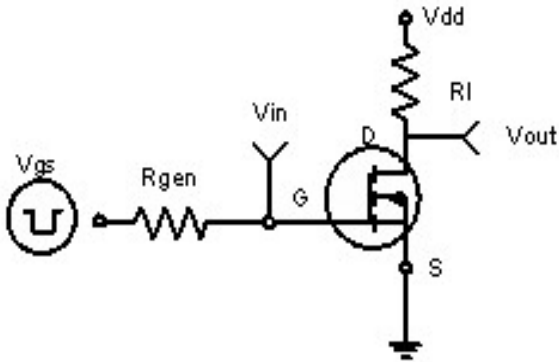


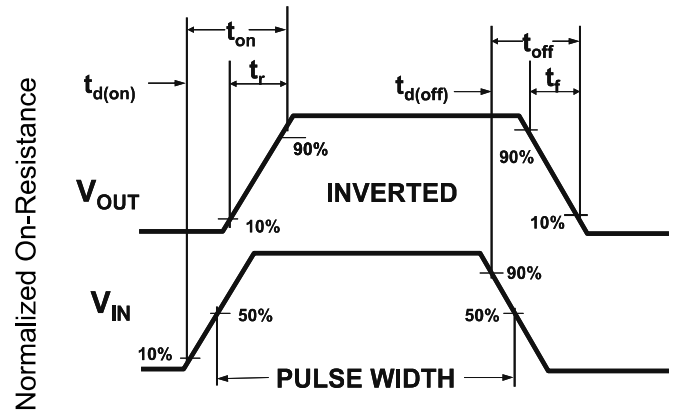
Figure 13 Normalized Maximum Transient Thermal Impedance



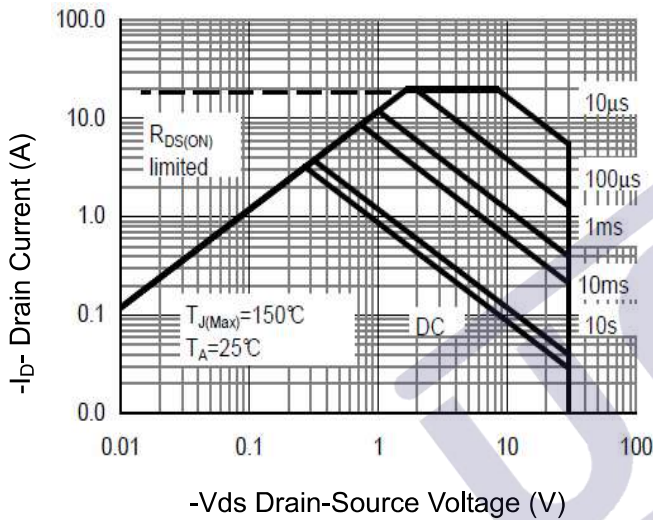
**P- Channel Typical Electrical and Thermal Characteristics**



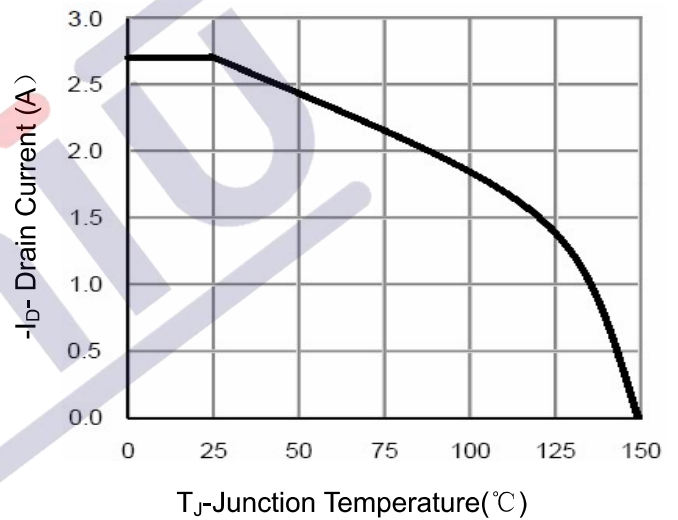
**Figure 1: Switching Test Circuit**



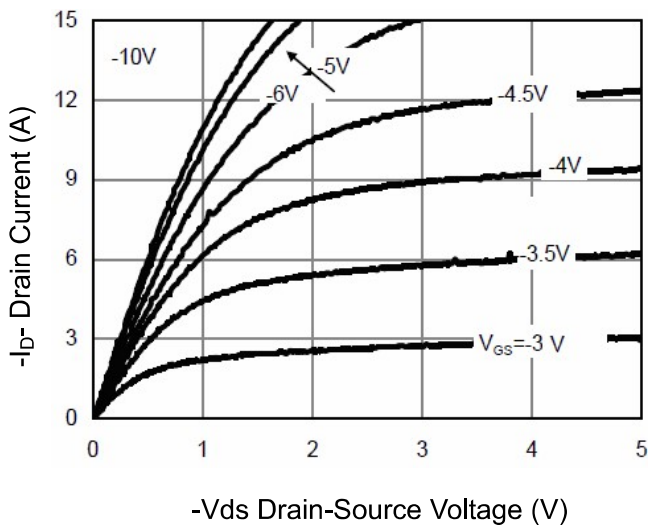
**Figure 2: Switching Waveforms**



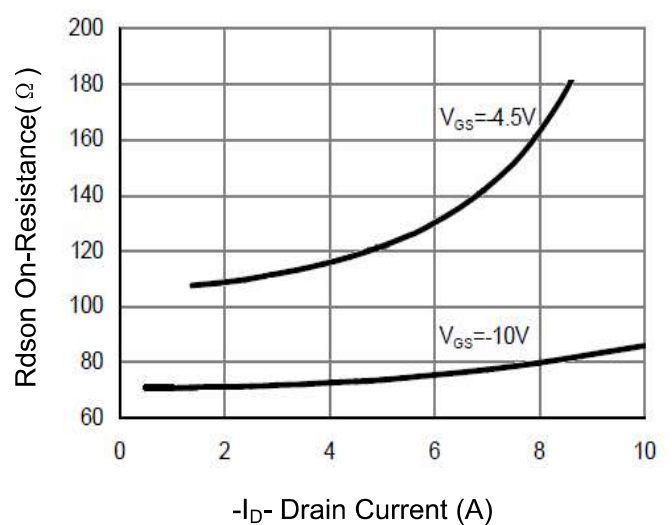
**Figure 3 Safe Operation Area**



**Figure 4 Drain Current**



**Figure 5 Output Characteristics**



**Figure 6 Drain-Source On-Resistance**



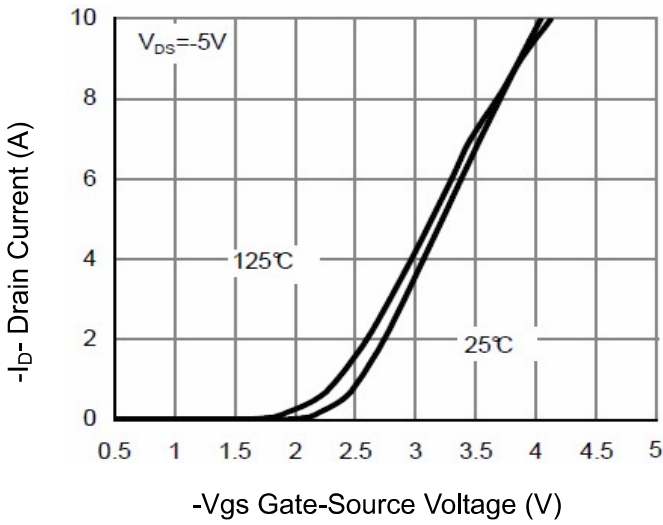


Figure 7 Transfer Characteristics

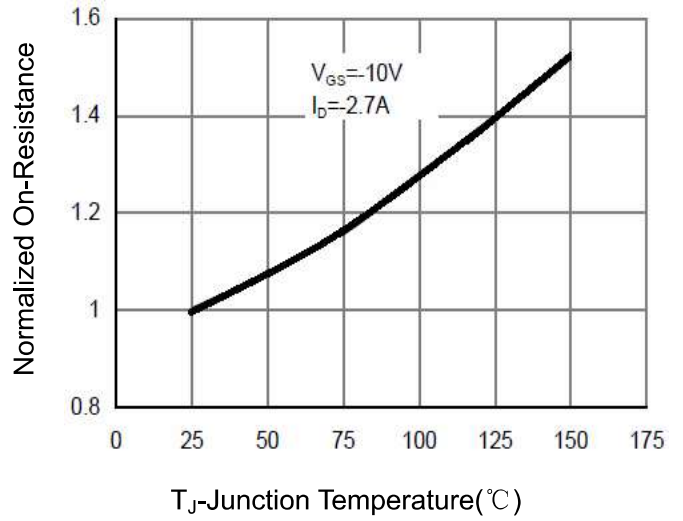


Figure 8 Drain-Source On-Resistance

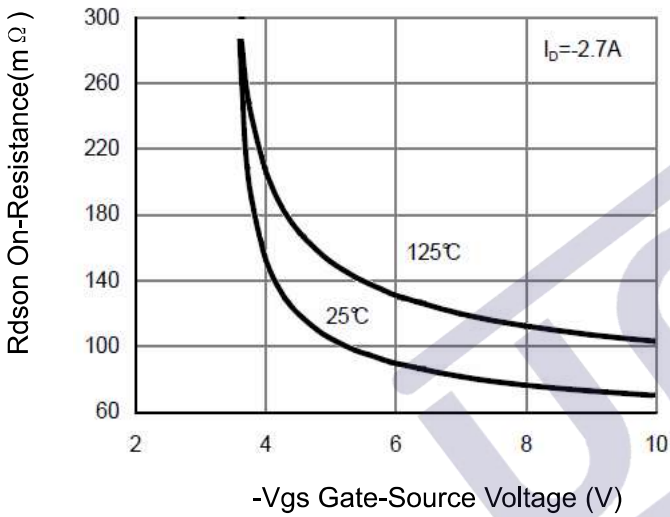


Figure 9 Rdson vs Vgs

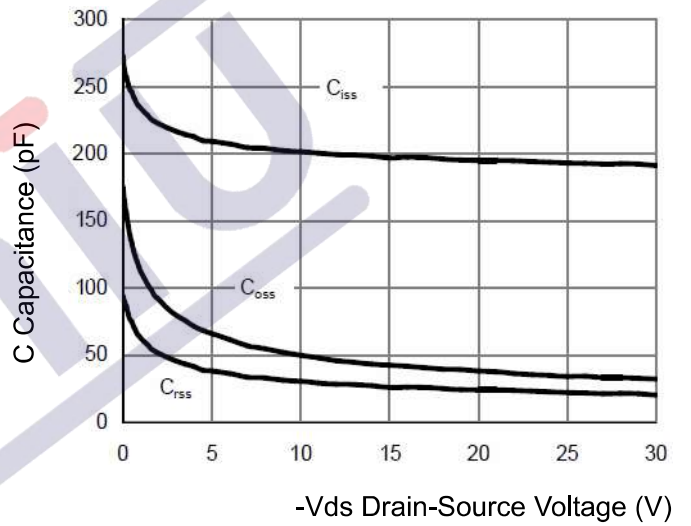


Figure 10 Capacitance vs Vds

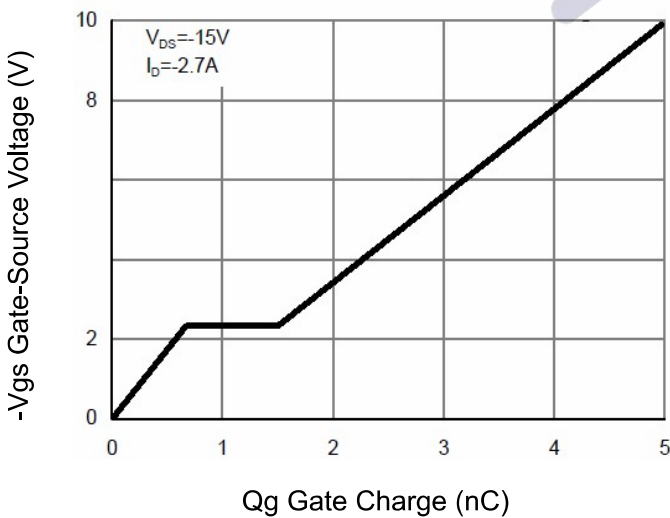


Figure 11 Gate Charge

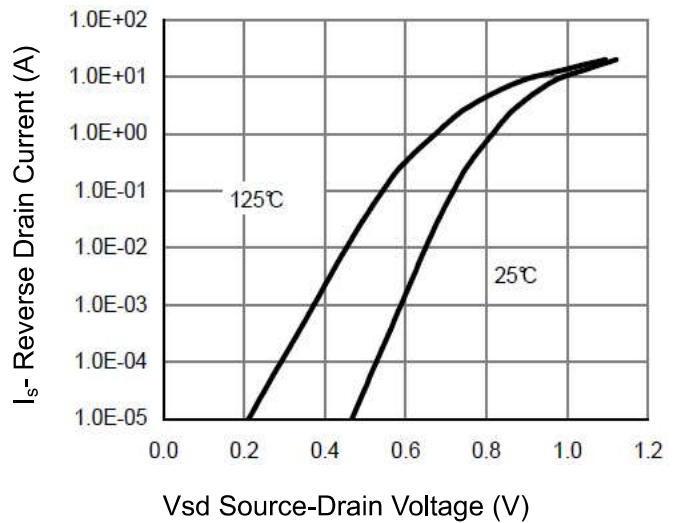
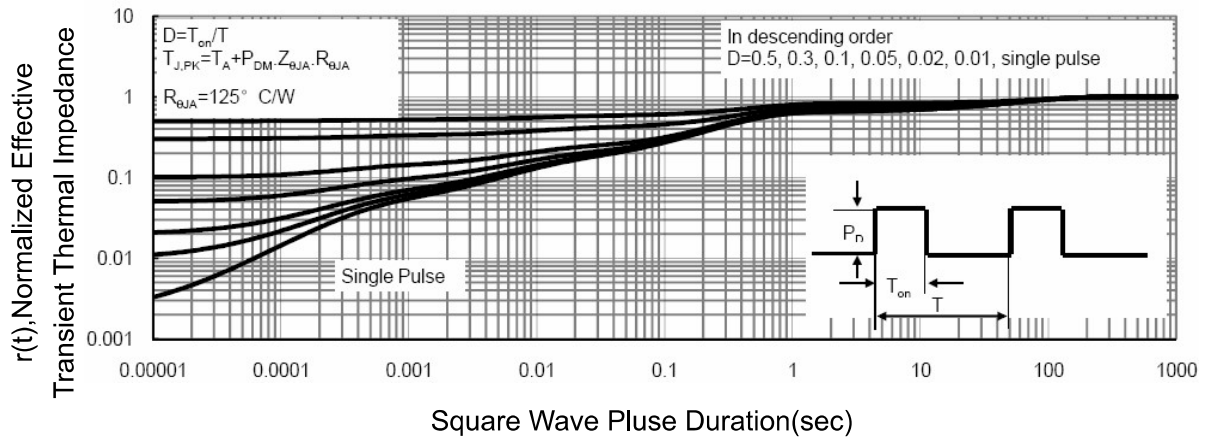


Figure 12 Source- Drain Diode Forward



**Figure 13 Normalized Maximum Transient Thermal Impedance**



## 1.版本记录

DATE	REV.	DESCRIPTION
2018/11/15	1.0	First Release
2020/09/18	1.1	Layout adjustment

## 2.免责声明

浙江宇力微新能源科技有限公司保留对本文档的更改和解释权力，不另行通知！客户在下单前应获取我司最新版本资料，并验证相关信息是否最新和完整。量产方案需使用方自行验证并自担所有批量风险责任。未经我司授权，该文件不得私自复制和修改。产品不断提升，以追求高品质、稳定性强、可靠性高、环保、节能、高效为目标，我司将竭诚为客户提供性价比高的系统开发方案、技术支持等更优秀的服务。

版权所有 浙江宇力微新能源科技有限公司/绍兴宇力半导体有限公司

## 3.联系我们

浙江宇力微新能源科技有限公司

总部地址：绍兴市越城区斗门街道袍渎路25号中节能科创园45幢4/5楼

电话：0575-85087896（研发部）

传真：0575-88125157

E-mail: htw@uni-semic.com

无锡地址：无锡市锡山区先锋中路6号中国电子（无锡）数字芯城1#综合楼503室

电话：0510-85297939

E-mail: zh@uni-semic.com

深圳地址：深圳市宝安区西乡街道南昌社区宝源路泳辉国际商务大厦410

电话：0755-84510976

E-mail: htw@uni-semic.com